onsemi

NPN Silicon Planar Epitaxial Transistor PZT651

This NPN Silicon Epitaxial transistor is designed for use in industrial and consumer applications. The device is housed in the SOT-223 package which is designed for medium power surface mount applications.

SOT-223 package ensures level mounting, resulting in improved thermal conduction, and allows visual inspection of soldered joints. The formed leads absorb thermal stress during soldering, eliminating the possibility of damage to the die.

Features

- High Current
- The SOT-223 Package can be Soldered Using Wave or Reflow
- PNP Complement is PZT751T1G
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	60	Vdc
Collector-Base Voltage	V _{CBO}	80	Vdc
Emitter-Base Voltage	V _{EBO}	5.0	Vdc
Collector Current	Ι _C	2.0	Adc
Total Power Dissipation @ T _A = 25°C (Note 1) Derate above 25°C	P _D	0.8 6.4	W mW/°C
Storage Temperature Range	T _{stg}	-65 to 150	°C
Junction Temperature	TJ	150	°C

THERMAL CHARACTERISTICS

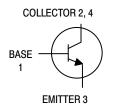
Characteristic	Symbol	Max	Unit
Thermal Resistance from Junction-to-Ambient in Free Air	$R_{\theta JA}$	156	°C/W
Maximum Temperature for Soldering Purposes	ΤL	260	°C
Time in Solder Bath		10	Sec

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

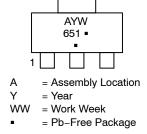
1. Device mounted on a FR-4 glass epoxy printed circuit board using minimum recommended footprint.

SOT-223 PACKAGE HIGH CURRENT NPN SILICON TRANSISTOR SURFACE MOUNT





MARKING DIAGRAM



(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
PZT651T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
SPZT651T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PZT651

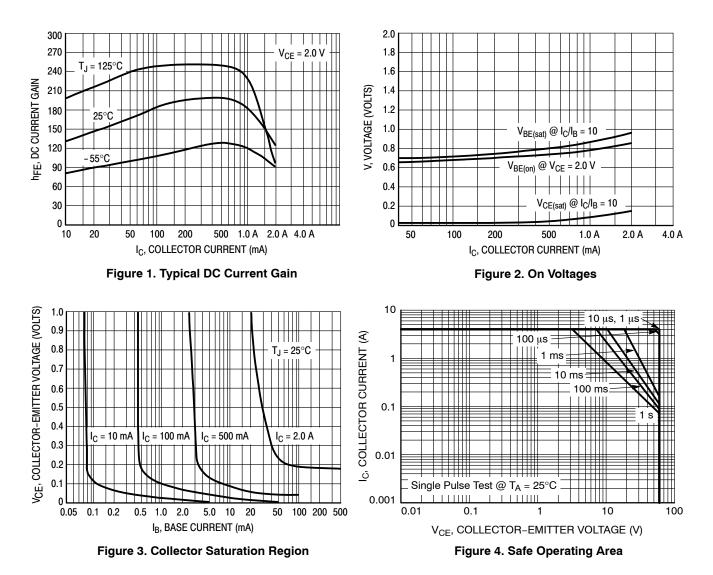
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristics	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage $(I_C = 10 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	60	_	Vdc
Collector–Emitter Breakdown Voltage ($I_C = 100 \ \mu Adc, I_E = 0$)	V _(BR) CBO	80	-	Vdc
Emitter-Base Breakdown Voltage ($I_E = 10 \ \mu Adc, I_C = 0$)	V _{(BR)EBO}	5.0	-	Vdc
Base-Emitter Cutoff Current (V _{EB} = 4.0 Vdc)	I _{EBO}	_	0.1	μAdc
Collector-Base Cutoff Current (V_{CB} = 80 Vdc, I _E = 0)	I _{CBO}	_	100	nAdc
ON CHARACTERISTICS (Note 2)				
$ \begin{array}{l} \text{DC Current Gain} \\ (I_{C} = 50 \text{ mAdc}, \text{ V}_{CE} = 2.0 \text{ Vdc}) \\ (I_{C} = 500 \text{ mAdc}, \text{ V}_{CE} = 2.0 \text{ Vdc}) \\ (I_{C} = 1.0 \text{ Adc}, \text{ V}_{CE} = 2.0 \text{ Vdc}) \\ (I_{C} = 2.0 \text{ Adc}, \text{ V}_{CE} = 2.0 \text{ Vdc}) \end{array} $	h _{FE}	75 75 75 40	- - - -	-
Collector-Emitter Saturation Voltages ($I_C = 2.0 \text{ Adc}, I_B = 200 \text{ mAdc}$) ($I_C = 1.0 \text{ Adc}, I_B = 100 \text{ mAdc}$)	V _{CE(sat)}		0.5 0.3	Vdc
Base-Emitter Voltages (I _C = 1.0 Adc, V _{CE} = 2.0 Vdc)	V _{BE(on)}	_	1.0	Vdc
Base-Emitter Saturation Voltage $(I_C = 1.0 \text{ Adc}, I_B = 100 \text{ mAdc})$	V _{BE(sat)}	_	1.2	Vdc
Current–Gain — Bandwidth (I _C = 50 mAdc, V _{CE} = 5.0 Vdc, f = 100 MHz)	f _T	75	_	MHz

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle = 2.0%

PZT651

TYPICAL CHARACTERISTICS



DATE 02 OCT 2018

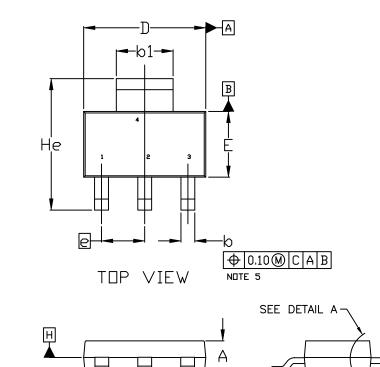




SCALE 1:1

0.10 C

A1



11

SIDE VIEW

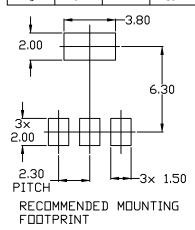
DETAIL A

NDTES:

SOT-223 (TO-261) CASE 318E-04 ISSUE R

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- 5. ALLIS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST PDINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS 6 AND 61.

	MILLIMETERS			
DIM	MIN.	NDM.	MAX.	
A	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
b	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
с	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
e	2.30 BSC			
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0*		10*	



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FRONT VIEW

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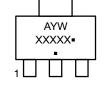
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SOT-223 (TO-261) CASE 318E-04 ISSUE R

DATE 02 OCT 2018

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	Style 9: Pin 1. Input 2. Ground 3. Logic 4. Ground	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	Style 12: Pin 1. Input 2. Output 3. NC 4. Output	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- Y = Year
- W = Work Week
- XXXXX = Specific Device Code
- = Pb-Free Package
- (Note: Microdot may be in either location) *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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